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FIG.1A

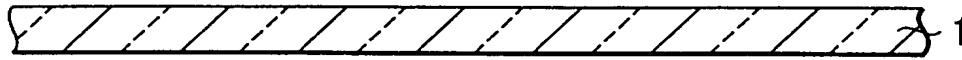


FIG.1B



FIG.1C

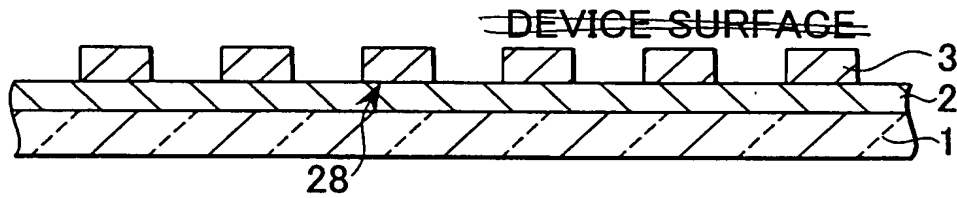


FIG.1D

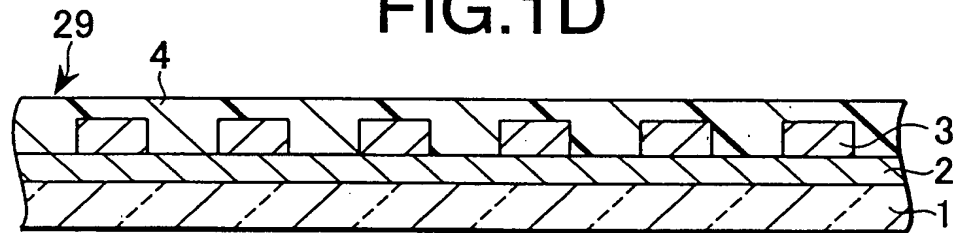
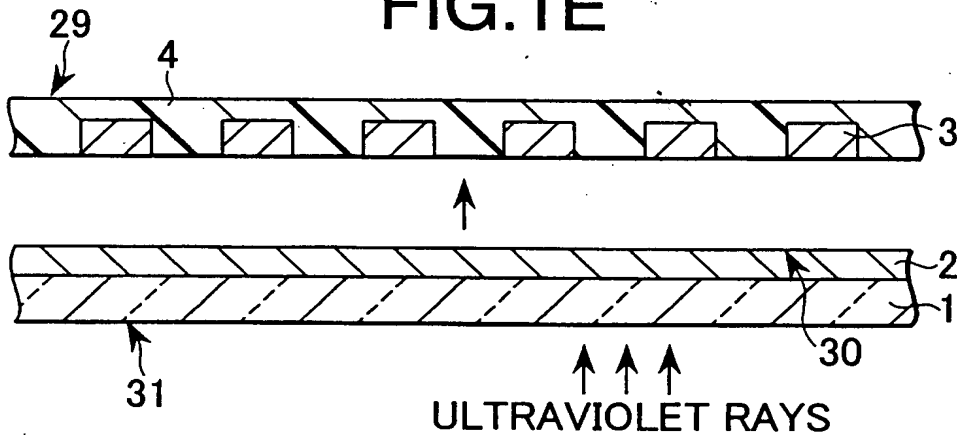
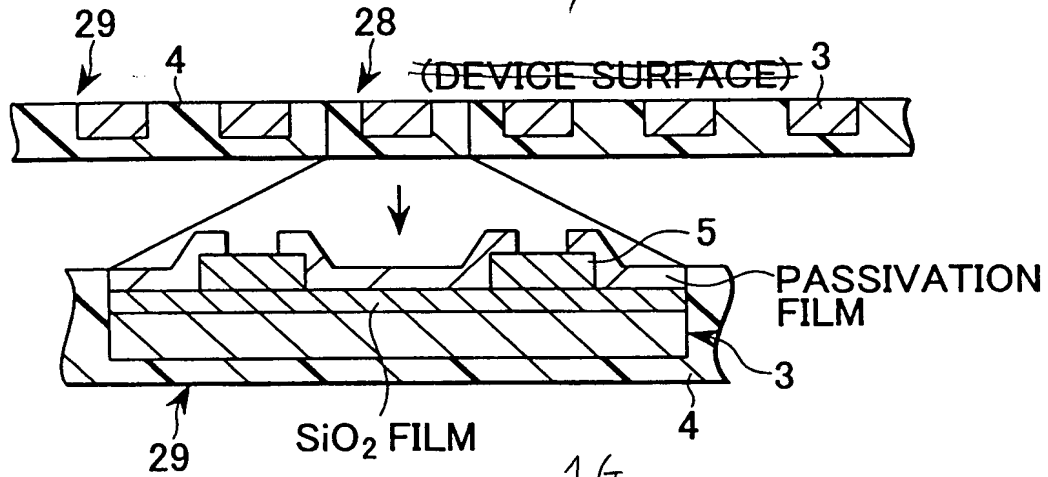


FIG.1E

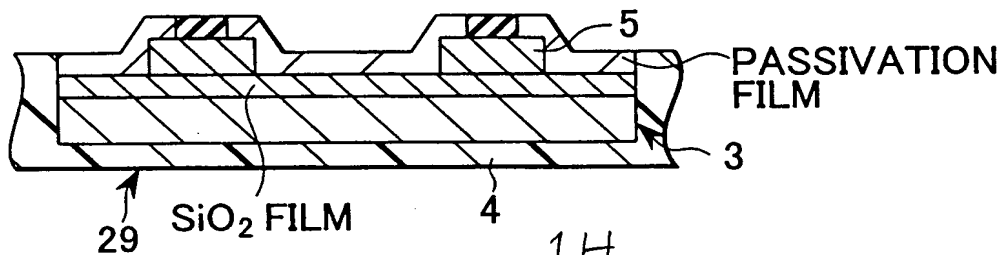


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1F  
**FIG. 2F**

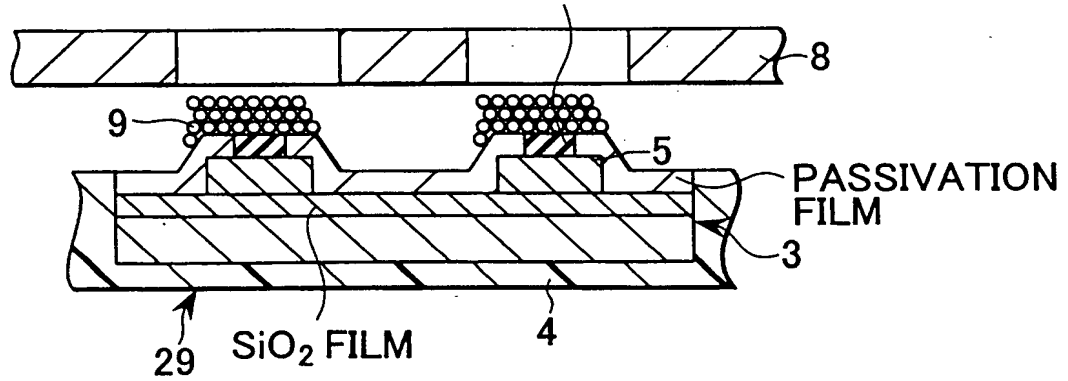


1G  
**FIG. 2G**



1H  
**FIG. 2H**

Ni ELECTROLESS  
PLATING LAYER (UBM)



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FIG. 3I 1I

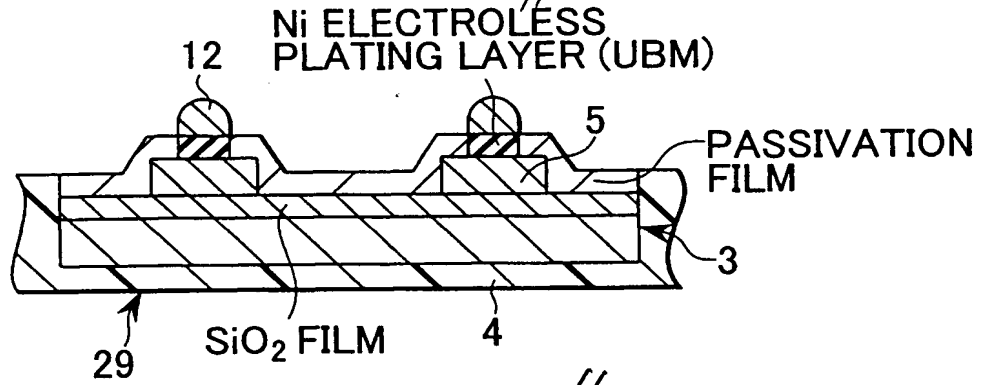


FIG. 3J 1J

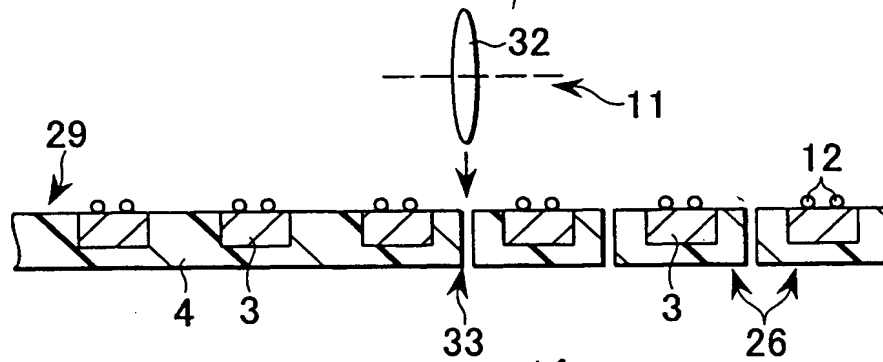


FIG. 3K 1K

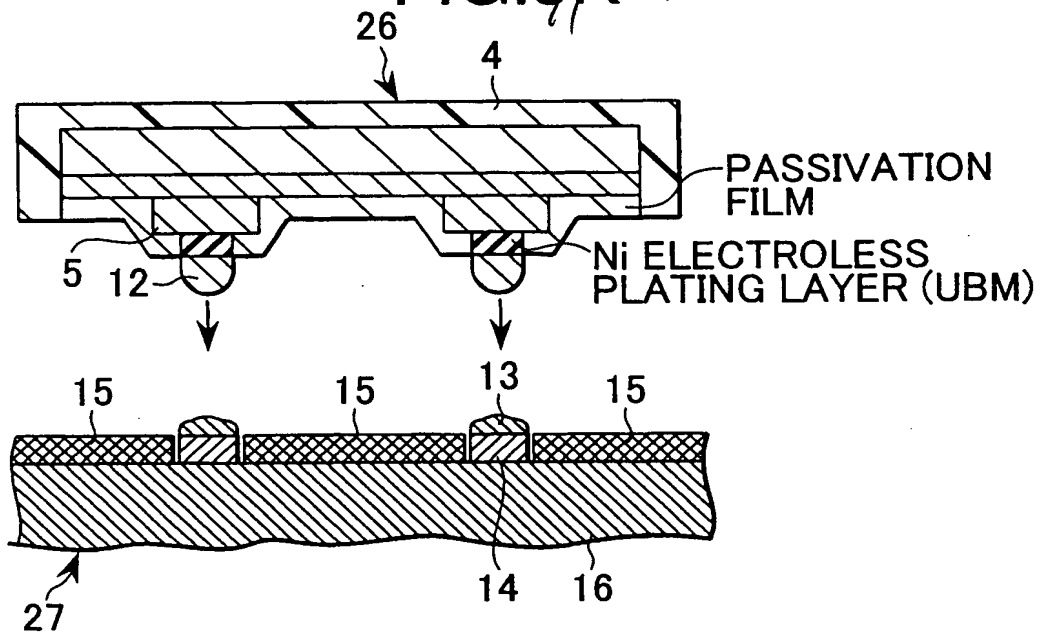
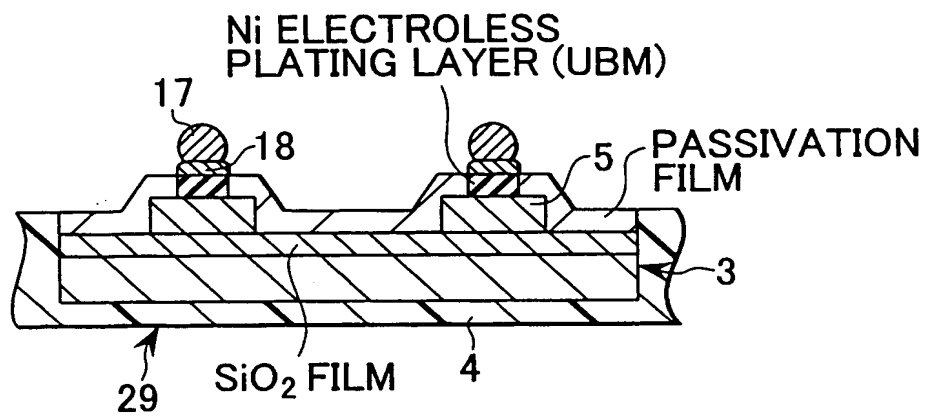


FIG. 4<sup>2</sup>



<sup>3</sup>  
~~FIG. 5~~

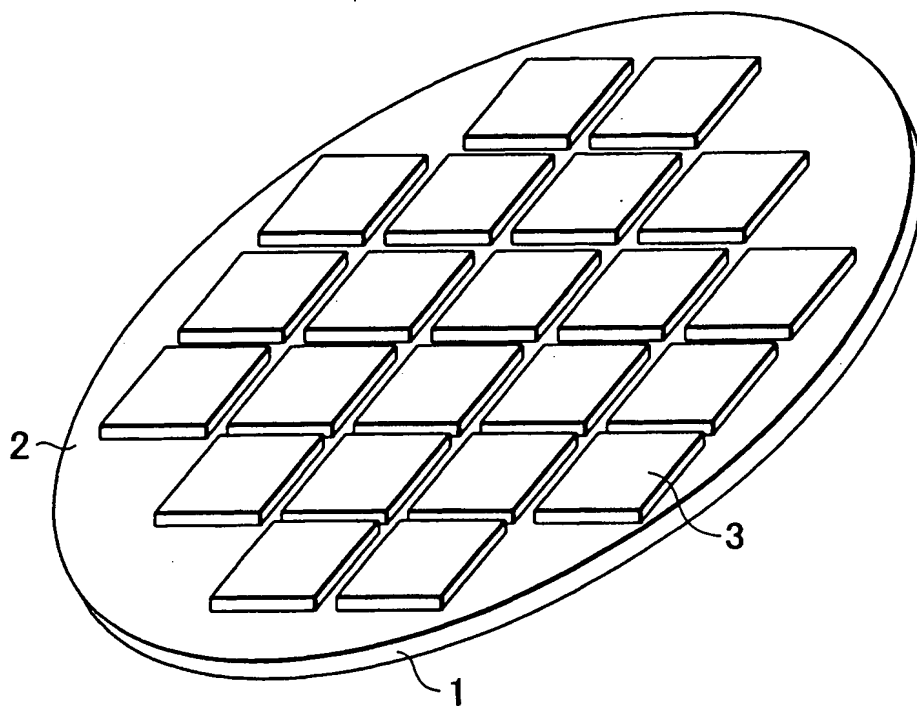
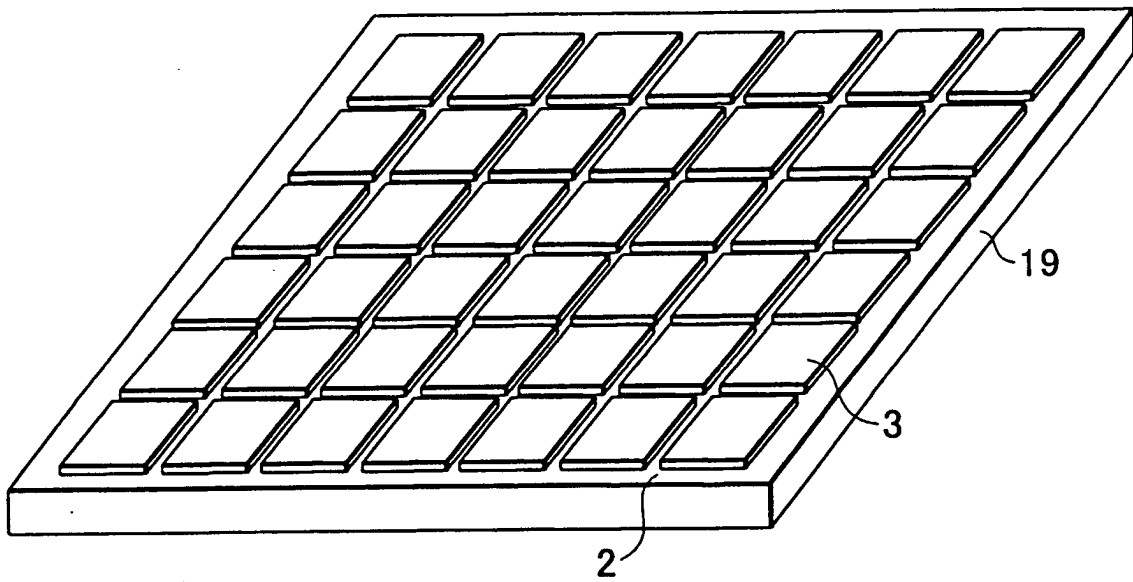


FIG. 5

4  
FIG. 6



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FIG. 7A 5A

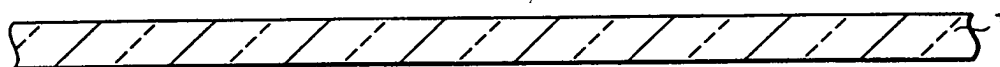


FIG. 7B 5B

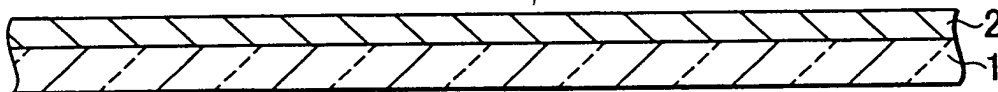


FIG. 7C 5C

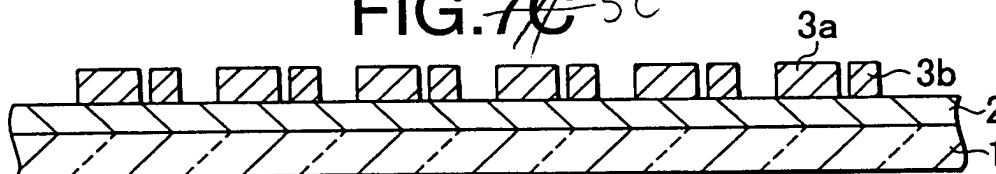


FIG. 7D 5D

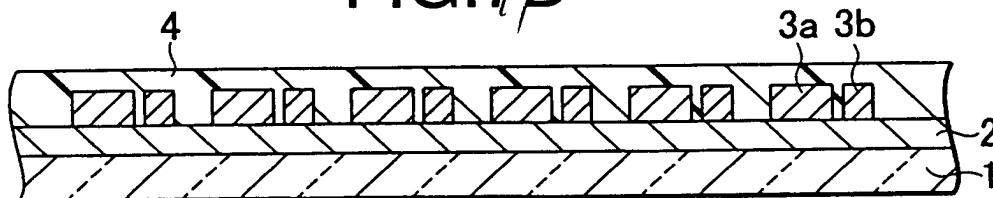
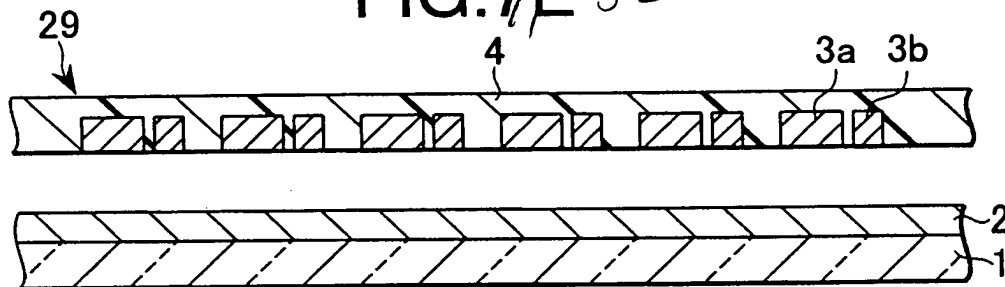


FIG. 7E 5E



↑ ↑ ↑  
ULTRAVIOLET  
RAYS

FIG. 8F 5F

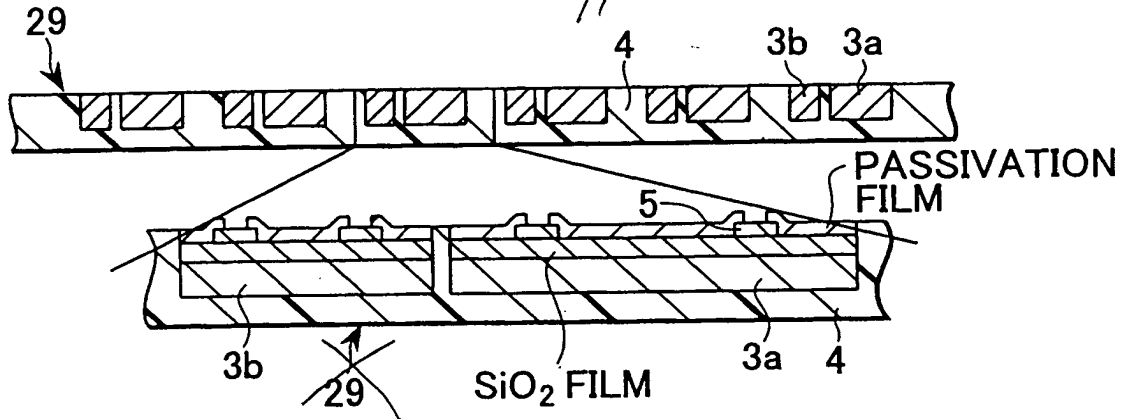


FIG. 8G 5G

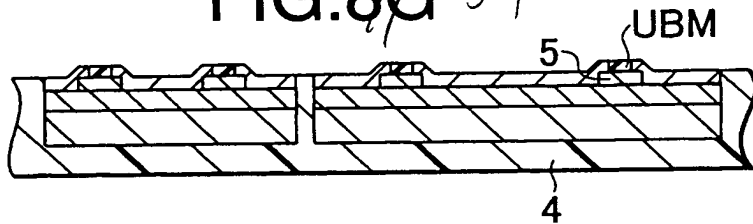


FIG. 8H 5H

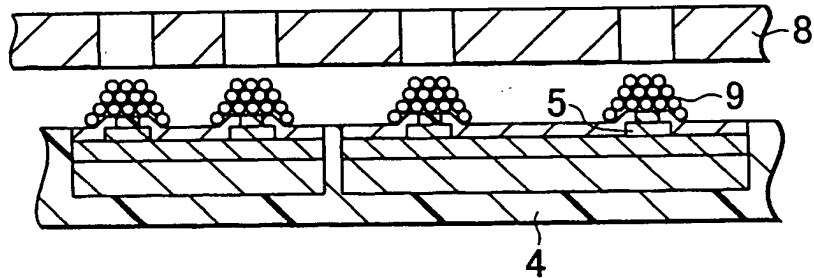




FIG. 9I 5I

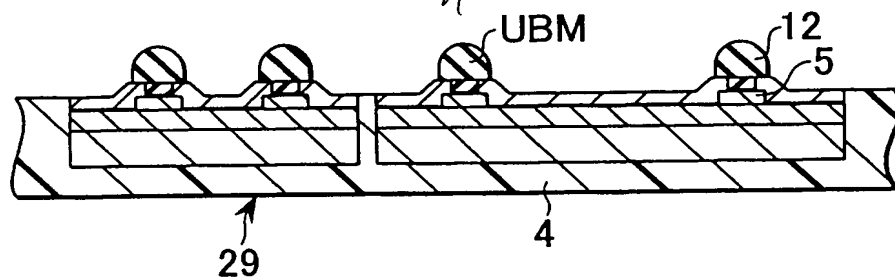


FIG. 9J 5J

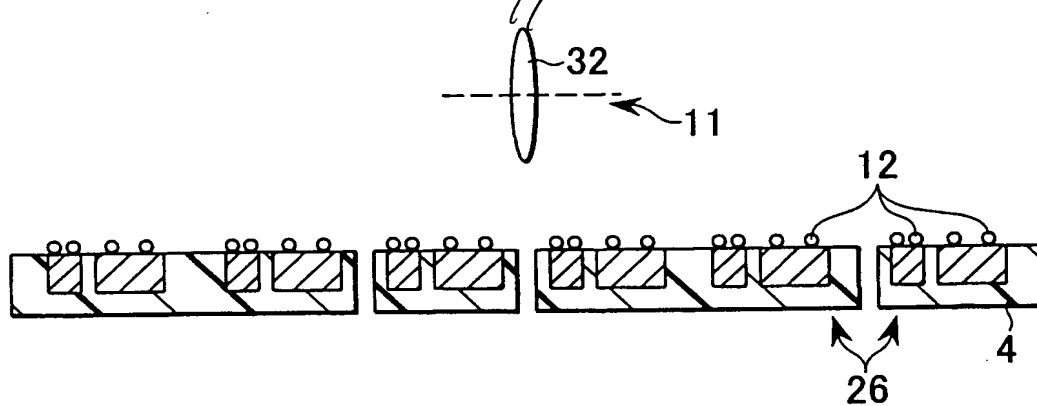


FIG. 10~~10~~<sup>6</sup>

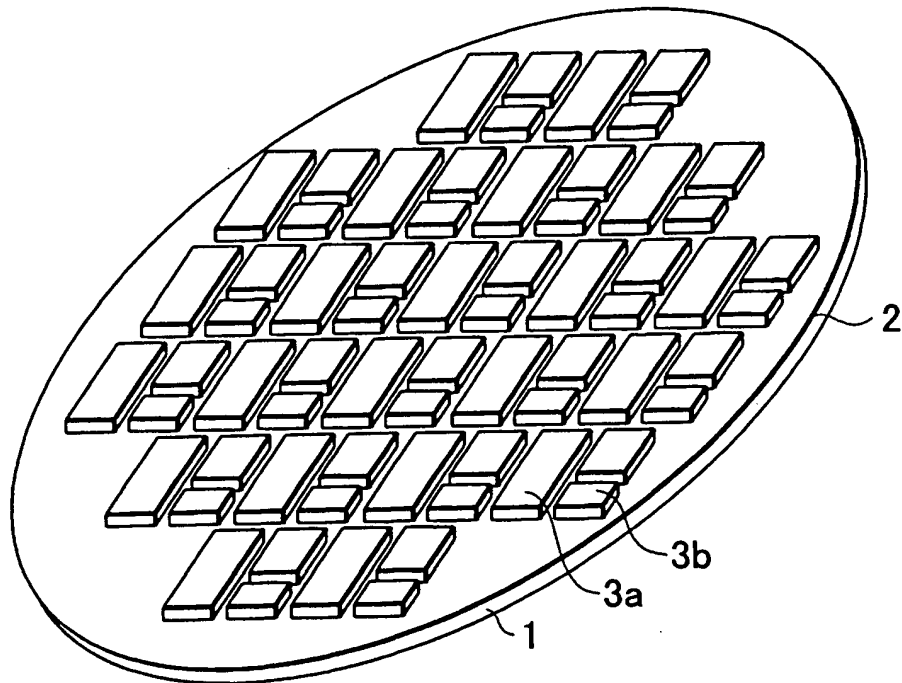


FIG. ~~11~~ 7

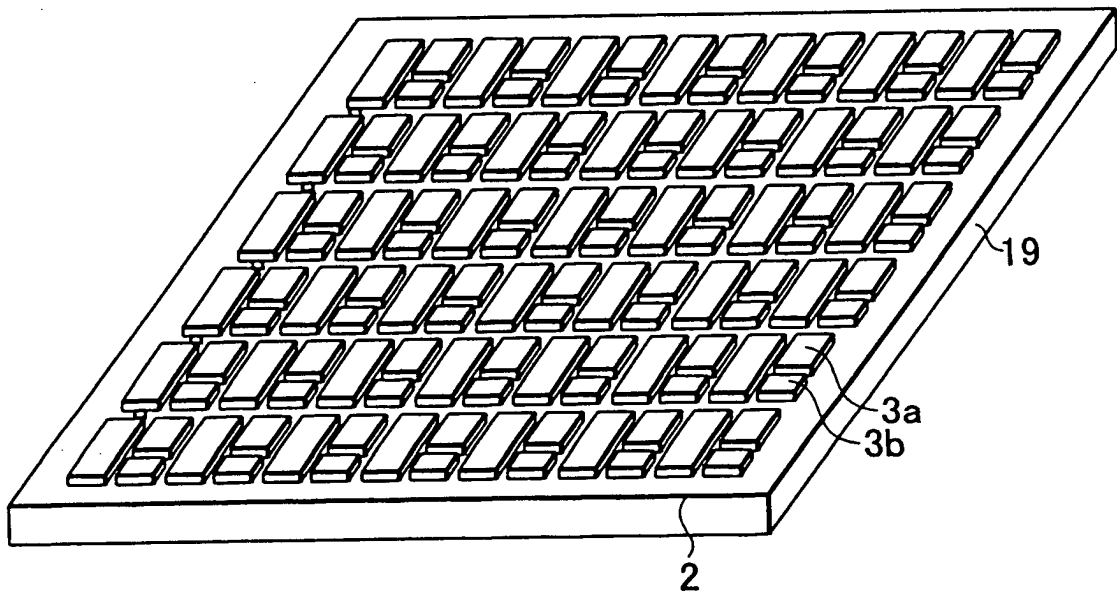


FIG. 12A 8A



FIG. 12B 8B

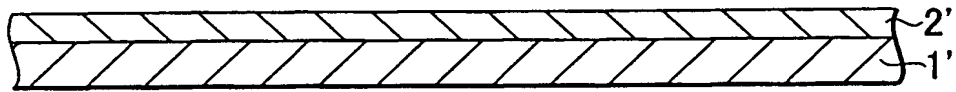


FIG. 12C 8C

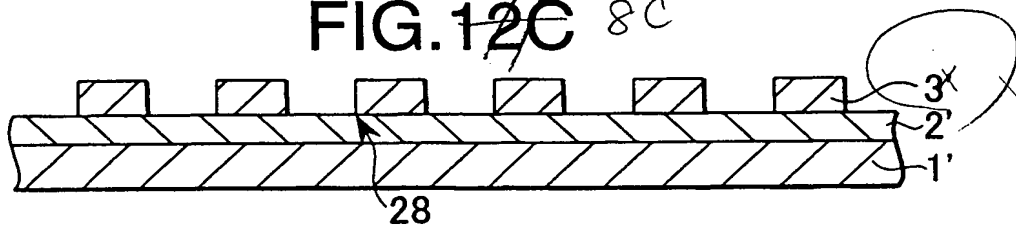


FIG. 12D 8D

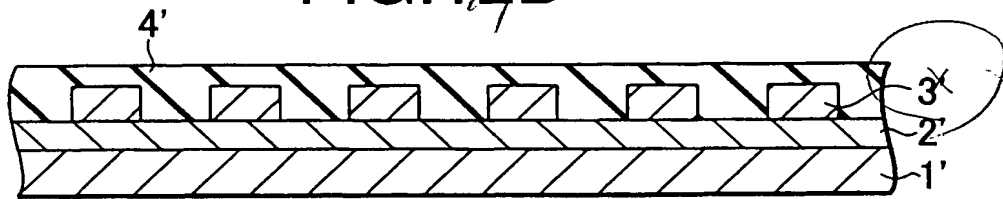
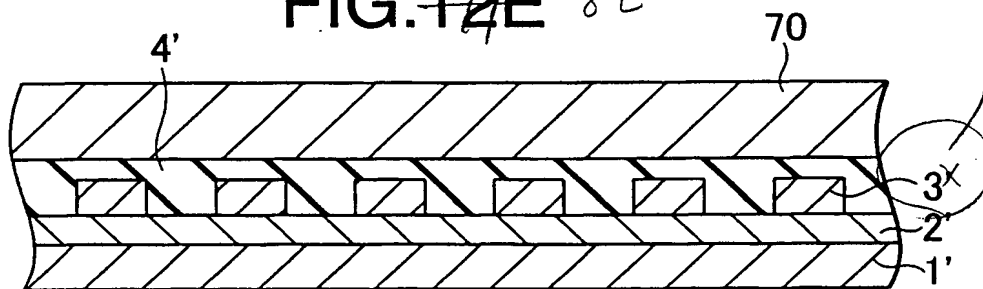


FIG. 12E 8E



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FIG. 13F 8F

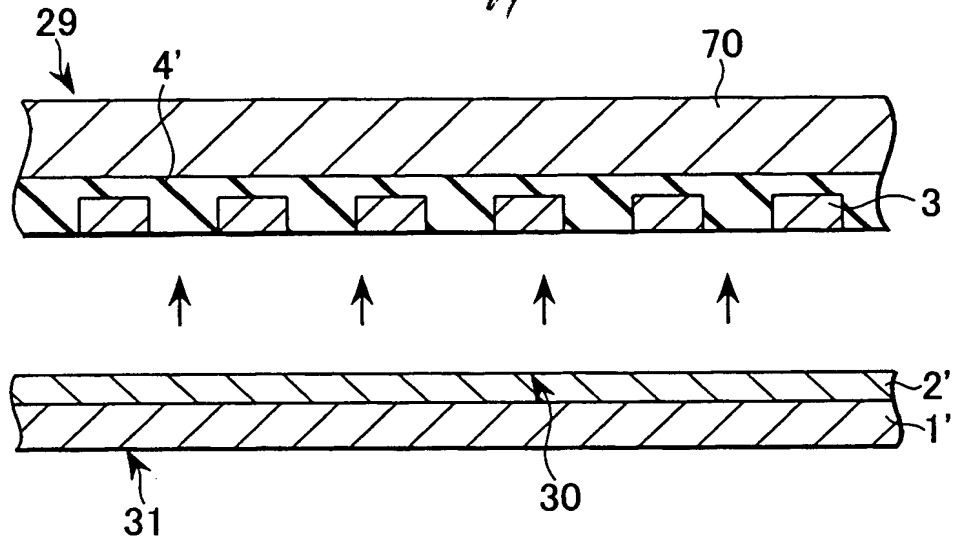


FIG. 13G 8G

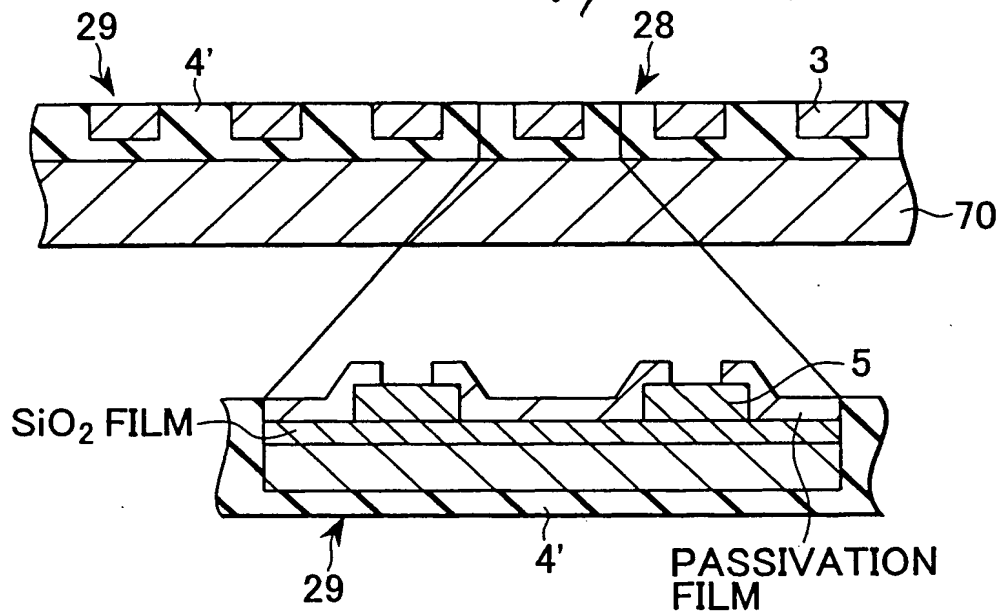


FIG. 14 9

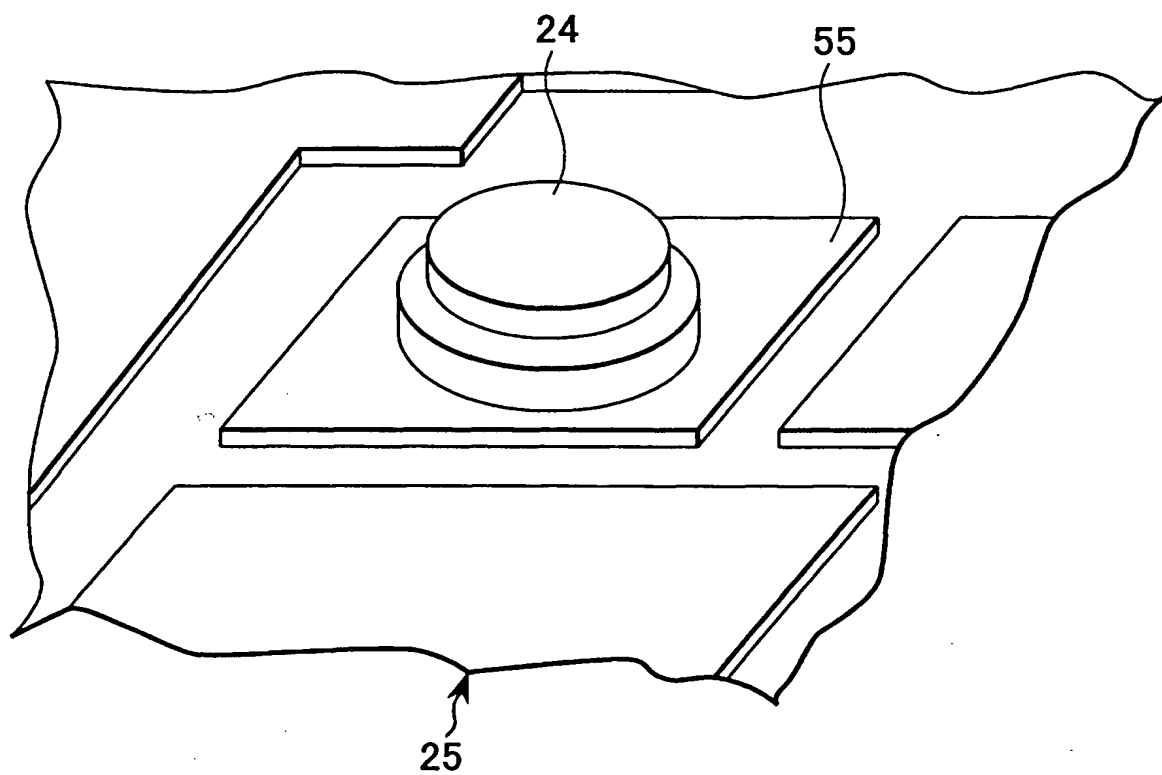


FIG. 15

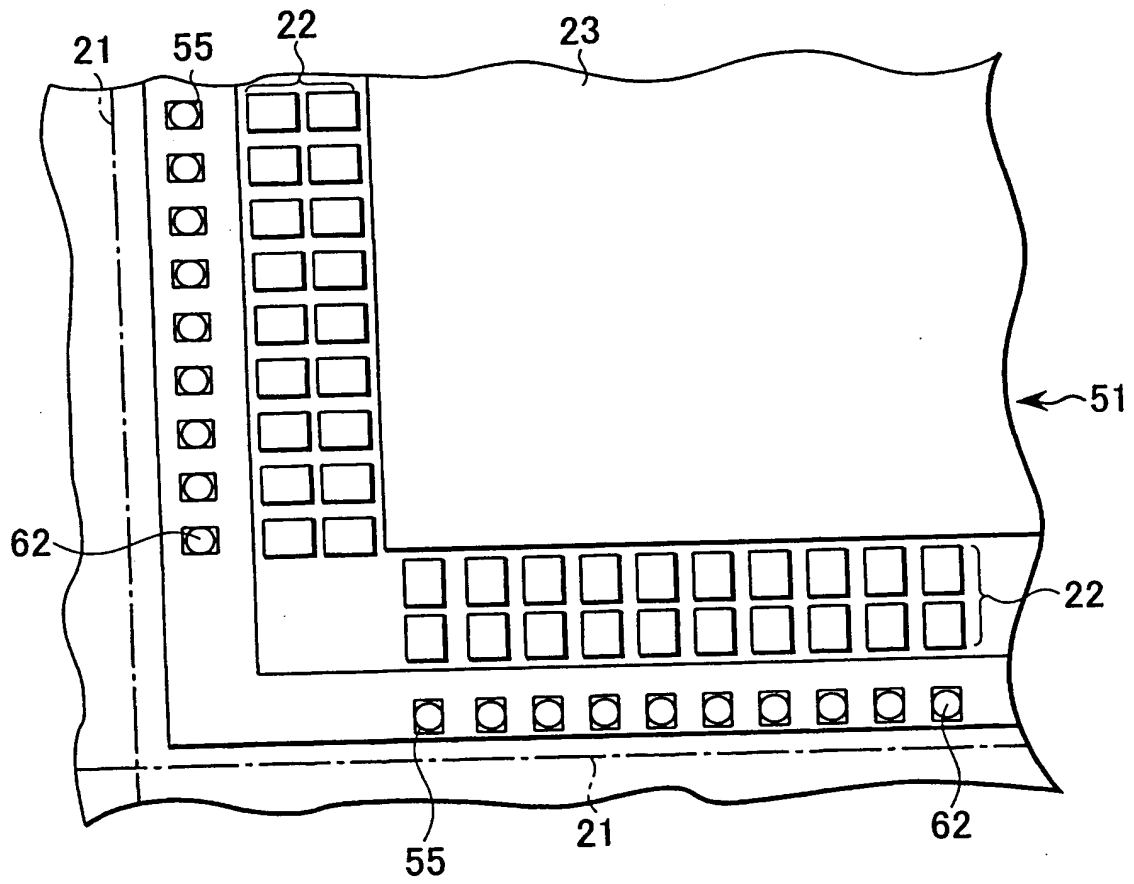
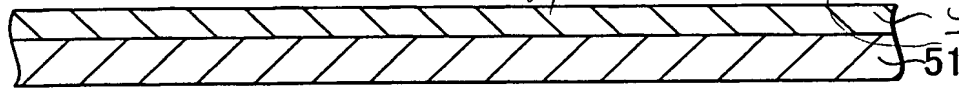


FIG. 16A

11A



SiO<sub>2</sub> FILM

FIG. 16B

11B

CHIP  
PORTION

PASSIVATION  
FILM

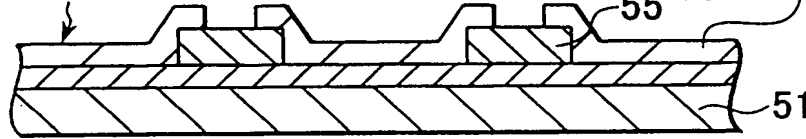
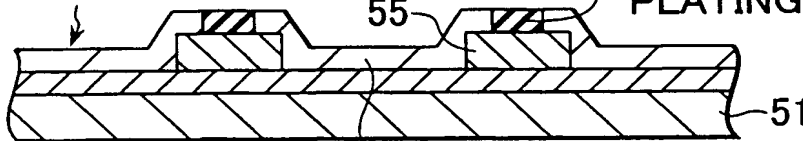


FIG. 16C

11C

CHIP  
PORTION

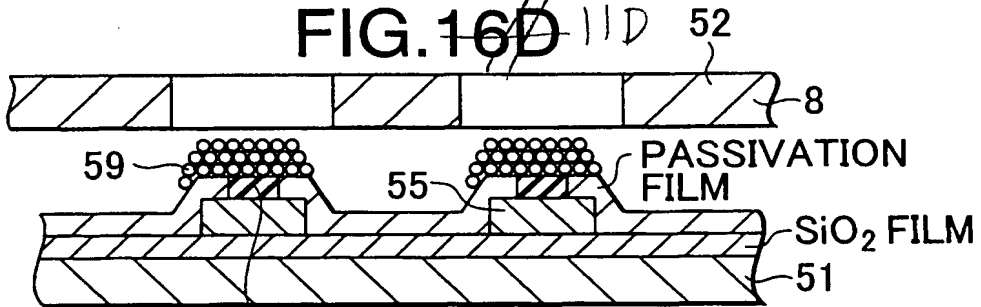
Ni ELECTROLESS  
PLATING LAYER (UBM)



PASSIVATION  
FILM

FIG. 16D

11D

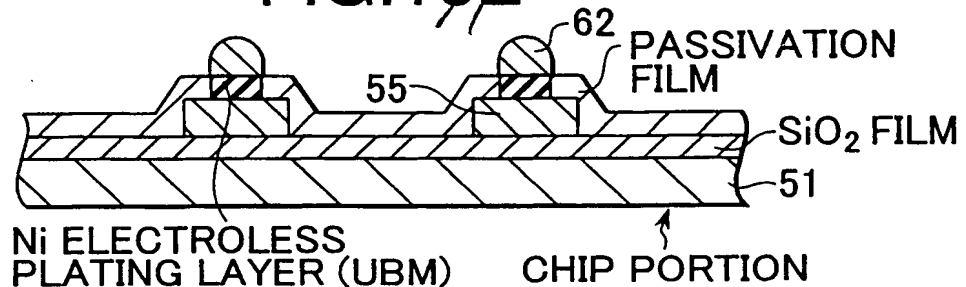


Ni ELECTROLESS  
PLATING LAYER (UBM)

CHIP PORTION

FIG. 16E

11E



Ni ELECTROLESS  
PLATING LAYER (UBM)

CHIP PORTION



FIG. 17 12 A

(a)

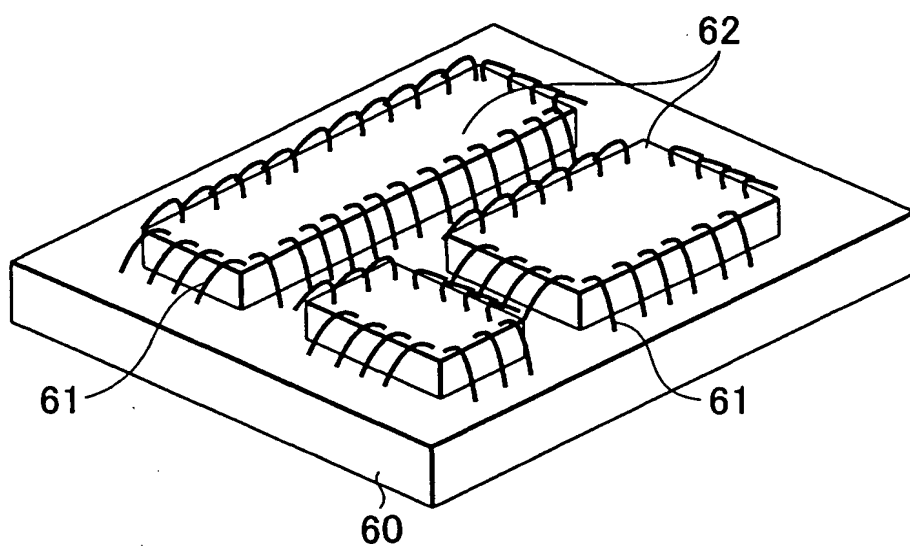


FIG. 12B

(b)

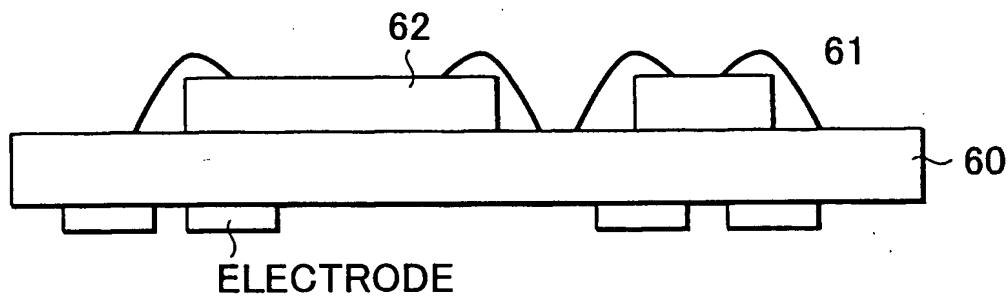


FIG. 18A 13A

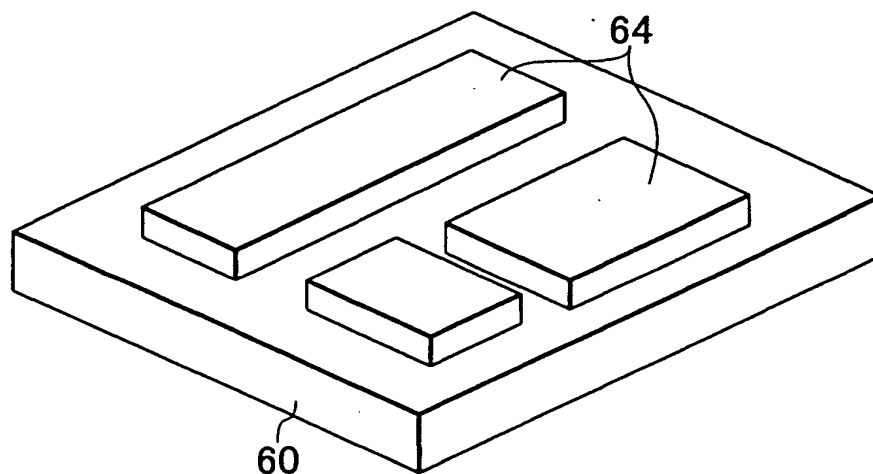


FIG. 18B 13B

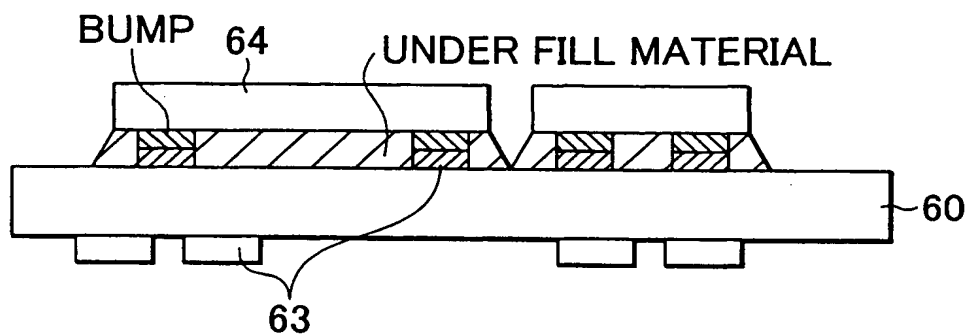
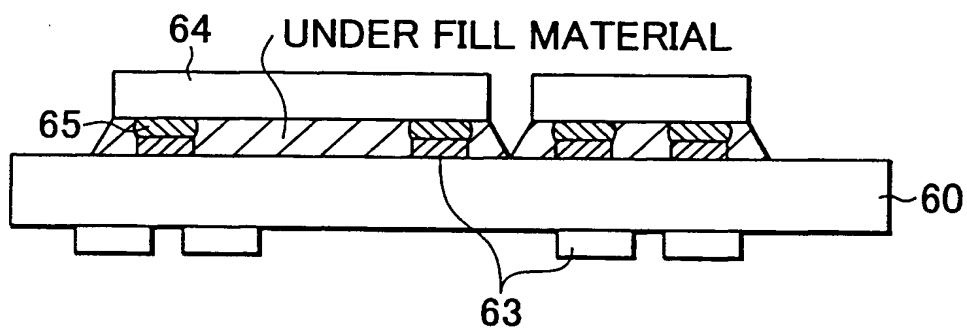


FIG. 18C 13C



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